

Abstract of the Disclosure

A conducting thick film composition, a thick film electrode made by sintering this composition, and a ceramic electronic component and a laminated ceramic capacitor in which this thick film electrode is used of which the electrical reliability is improved by the strength of a bond between a ceramic substrate and a thick film electrode being increased by the elimination of blistering and cracking of the electrode during sintering of the composition and the adherence of solder to the electrode being improved by the elimination of glass separation out onto the surface of the electrode during sintering.

The conducting thick film composition comprises Cu powder, glass powder and an organic vehicle, the Cu powder comprises spherical powder and scaly powder and the glass powder comprises borosilicate zinc glass and borosilicate barium glass.

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